

EAST - [luan1.wsp:1]

File View Edit Tools Window Help

Pending

Active

- L1: (10128) (mobile adj telephone)
- L2: (797) (1 AND HOUSING)
- L3: (0) 2 and (capping adj layer)
- L4: (152) (2 AND (CIRCUIT ADJ BOARD))
- L5: (0) 4 and (resin adj layer)
- L6: (4) (4 AND ENCAPSULATED)
- L7: (1) (6 AND LAYER)
- L8: (0) 2 and (synthesis adj resin)
- L9: (3) ((361/816.CCLS.) AND (PORTABLE ADJ APPARATUS))
- L10: (0) 9 and (encapsulated adj layer)
- L11: (0) 361/816.ccls. and (encapsulated adj layer)
- L12: (0) 361/737.ccls. and (capping adj layer)
- L13: (801) 361/752.CCLS.
- L14: (755) 361/748.CCLS.
- L15: (73) 361/712.CCLS.
- L16: (397) 361/719.CCLS.

Failed

- (0) 5 same (non adj electrically adj conductive)

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DBs USPAT: USDCR: EPD: JPO: Derwent

361/719

BRS form ISR form Image Text

	U		Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	EP 281404 A2	19880907	8	Cooling system for electronic equipment.		361/719
2	<input type="checkbox"/>	<input type="checkbox"/>	EP 340520 A2	19891108	5	Convection-cooling arrangement for electrical		361/719
3	<input type="checkbox"/>	<input type="checkbox"/>	DE 4118397 A1	19921210	4	Metal-cored circuit board carrying integrated circuit		174/15.1 ; 361/719
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	EP 521720 A1	19930107		Heat-dissipating multi-layer circuit board.		361/719
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	EP 577099 A2	19940105		Cooling apparatus for electronic elements.		361/719
6	<input type="checkbox"/>	<input type="checkbox"/>	EP 4220066 A1	19940112		Heat-dissipating multi-layer circuit board.		174/15.1

Hits Details